

2018 34th Thermal Measurement, Modeling & Management Symposium (SEMI-THERM 2018)

**San Jose, California, USA
19 – 23 March 2018**



**IEEE Catalog Number: CFP18SEM-POD
ISBN: 978-1-5386-4403-4**

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IEEE Catalog Number:	CFP18SEM-POD
ISBN (Print-On-Demand):	978-1-5386-4403-4
ISBN (Online):	978-1-5386-4402-7
ISSN:	1065-2221

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